- 1 "2002 - 0 "2002 - 93 257/6 same	conductor or die or chip or IC) and g near substrate with material with	USPAT; US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB;	Time stamp 2004/05/03 0 2004/04/26 2 2004/05/03 0 2004/05/03 0	20:19
- 1 "2002 - 0 "2002 - 93 257/6 same	g near substrate with material with ic 0158327" 0158327" 91 and (main or power) with electrode (metal or copper or "Cu") 91 and (main or power) with electrode (metal or copper or "Cu") same is 4 or several) with (semiconductor	USPAT; US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/03 0 2004/05/03 0	05:38
- 0 "2002 257/6 same	0158327" 91 and (main or power) with electrode (metal or copper or "Cu") 91 and (main or power) with electrode (metal or copper or "Cu") same i\$4 or several) with (semiconductor	US-PGPUB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/03 0 2004/05/03 0	05:38
- 93 257/6 same - 3 257/6 same	91 and (main or power) with electrode (metal or copper or "Cu") 91 and (main or power) with electrode (metal or copper or "Cu") same is 4 or several) with (semiconductor	USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/03 0	
- 3 257/6 same	(metal or copper or "Cu") 91 and (main or power) with electrode (metal or copper or "Cu") same i\$4 or several) with (semiconductor	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;		07:05
- 3 257/6 same	(metal or copper or "Cu") 91 and (main or power) with electrode (metal or copper or "Cu") same i\$4 or several) with (semiconductor	EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/03 0	
same	(metal or copper or "Cu") same i\$4 or several) with (semiconductor	USPAT;	2004/05/03 0	
	o or onep,	EPO; JPO; DERWENT;	2001, 00, 00)5:52
same (mult	91 and (main or power) with electrode (metal or copper or "Cu") same i\$4 or several or second) with conductor or die or chip or IC)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/03 0)5:52
same (mult	91 and (main or power) with electrode (metal or copper or "Cu") same i\$4 or several or second or lity) with (semiconductor or die or	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0	06:11
- 3 361/8 same (mult	or IC) 13 and (main or power) with electrode (metal or copper or "Cu") same is4 or several or second or	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/05/03 0	06:11
- 4 chip (361/ or po coppe	lity) with (semiconductor or die or or IC) 813 or 361/820 or 361/775) and (main wer) with electrode same (metal or or "Cu") same (multi\$4 or several cond or plurality) with	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0)6:16
- 4 (semi (361/ or po	conductor or die or chip or IC) 832 or 361/829 or 361/736) and (main wer) with electrode same (metal or r or "Cu") same (multi\$4 or several	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/05/03 0	06:18
or se (semi) - 5 (361/and () (meta	cond or plurality) with conductor or die or chip or IC) 781 or 361/783 or 361/752 or 361/753) main or power) with electrode same l or copper or "Cu") same (multi\$4 or	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/05/03 0)6:18
- (semi 57610 elect	al or second or plurality) with conductor or die or chip or IC) 40.pn. and (main or power) with rode and (metal or metallic or "Ni" ckel or copper or "Cu") with rode	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0)7:06
elect	40.pn. and (main or power) with rode and (metal or metallic or "Ni" ckel or copper or "Cu") same rode	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0)7:12
with	91 and (main or power) with electrode (metal or metallic or "Ni" or nickel pper or "Cu")	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0)7:21
	91 and (main or power) with electrode (metal or "Ni" or nickel or copper u")	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 0)7:21
with:	91 and (main or power) with electrode material with (metal or "Ni" or l or copper or "Cu")	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/03 0)7:22

-	610	(semiconductor or die or chip or IC) and	USPAT;	2004/05/03 09:11
		(main) with electrode with material with	US-PGPUB;	
		(metal or "Ni" or nickel or copper or	EPO; JPO;	
		"Cu")	DERWENT;	
			IBM_TDB	